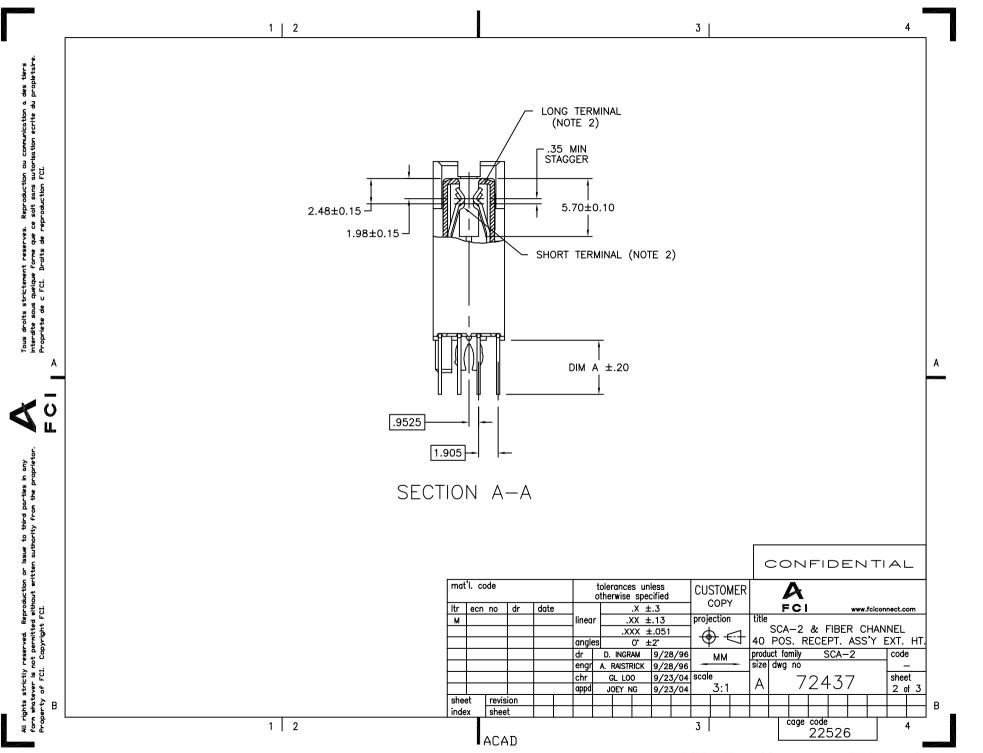


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3 1 | 2 POLARIZATION DIM A PI ATING PI ATING PI ATING PI ATING PRODUCT NO. RECOMMEDED P.C. BOARD THICKNESS PRODUCT NO. PRODUCT NO. PRODUCT NO. PEG 72437-101 72437-001 72437-001LF 72437-201LF 2.79 YES -001S -101S 1.57mm (0.062") -002 -102 -002LF -202LF 2.79 NO -002S -102S -003 -103-003LF -203LF 3.18 YES -0038 -103S NOTE 4 2.36mm (0.093") NOTE 6 NOTE 9 NOTE 8 -004 -104 -004LF -204LF 3.18 NO -0045 -1045-005 -105 72437-005LF 72437-205LF 4.06 YES -0055-105S3.18mm (0.125") -206LF -006 -106-006LF 4.06 NO -006S -106S-007-107-007LF -207LF 4.60 YFS 72437-007S 72437-107S NOTES: - SEE NOTE 6 SEE NOTE 9 SFF NOTE 8 — 34.11 (1) TRUE POSITION NOTES APPLY AT TERMINAL TIP. 2.70 ± 0.10 2.60±0.10 DIA POSN 40 POSN 21 NOTE 5 NOTE 5 CONTACTS IN POSITIONS 1 THRU 20,24,25,27,28, 30, 31, 33, AND 34 ARE SHORT TERMINALS. CONTACTS IN POSITIONS 21, 22, 23, 26, 29, 32, AND 35 THRU 40 ARE LONG TERMINALS. 1.90 TYP. - 2.20±0.10 0 0 0 0 0 0 NOTE 5 RAW MATERIALS: 0 0 0 0 0 0 0 O HOUSING: HTN, UL94V-O, COLOR: BLACK 0 0 0 0 0 CONTACTS: PHOSPHOR-BRONZE .95 0 0 0 0 0 0 CONTACT PLATING: 30u" (0.76um) MIN. GXT PLATING TYP. OVER 50u" (1.27um) NICKLE MIN. UNDERPLATE IN CONTACT AREA. 100μ" (2,54μm) MIN TIN-LEAD PLATING OVER 50μ" (1,27μm) MIN 2.60±0.10 DIA. NICKEL UNDERPLATE IN P.C. BOARD LEG AREA. -Y-50u"(1.27um) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. ∠2.60±0.10 DIA 0.80±0.08 DIA POSN 1 DIMENSIONS DO NOT APPLY TO CONNECTOR STYLES 1.27 WITHOUT POLARIZATION PEG. (SEE CHART) RECOMMENDED PC BOARD TYP 40 PLC POSN 20 4.99 CONTACT PLATING: 30µ" (0.76µM). MIN. GOLD PLATING MOUNTING DIMENSIONS OVER 50µ" (1.27µm) NICKLE MIN. UNDERPLATE IN CONTACT AREA. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK COMPONENT SIDE 100μ" (2,54μm) MIN TIN-LEAD PLATING OVER 50μ" (1,27μm) MIN TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION NICKLE UNDERPLATE IN P.C. BOARD LEG AREA. WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD. 50μ" (1.27μm) MIN. NICKLE UNDERPLATE OVER REMAINING AREA. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. PART NUMBERS WITH AN "S" SUFFIX ARE MANUFACTURED PART NUMBERS ENDING IN "LF" MEANS FOR NOTE 11 WITH A BRIGHT TIN-LEAD FINISH ON THE TERMINAL TAIL LEAD FREE IDENTIFICATION. P/N XXXXX-2XXLF IS EQUIVALENT SECTION. PART NUMBERS WITHOUT AN END SUFFIX ARE CONFIDENTIAL MANUFACTURED WITH MATTE TIN-LEAD FINISH OR MATTE TIN FINISH. TO PREVIOUS P/N XXXXX-2XX mat'l. code tolerances unless CONTACT PLATING: 30u" (0.76um) GOLD PLATING CUSTOMER otherwise specified OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA. COPY FCI 100u" (2,54um) - 100u"(5,08um) TIN PLATING OVER ltr ecn no dr date .x ±.3 www.fciconnect.com 50u" (1.27um) -100u" (2.54um) NICKEL UNDERPLATE IN М linear projection title .XX ±.13 SCA-2 & FIBER CHANNEL .XXX ±.051 P.C. BOARD LEG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER 40 POS. RECEPT. ASS'Y EXT. HT REMAINING AREA. 0° ±2° dr D. INGRAM 9/28/96 product family SCA-2 code MM CONTACT PLATING: 30u" (0.76um) GXT PLATING A. RAISTRICK 9/28/96 size dwg no OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA. engr 9/23/04 scale 100u" (2,54ùm) - 200u"(5,08um) TIN PLATING OVER chr GL LOO sheet 72437 2:1 50u" (1.27um) -100u" (2.54um) NICKEL UNDERPLATE IN appd JOEY NG 9/23/04 3 of 3 P.C. BOARD LEG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER revision REMAINING AREA. index sheet cage code 1 | 2 3

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